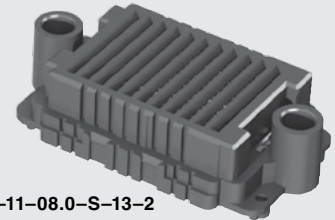


HDAM-11-12.0-S-13-2



HDAF-11-08.0-S-13-2

(2.00 mm) .0787"

HDAM, HDAF SERIES

RUGGED ELEVATED HIGH-DENSITY ARRAY

HDAM Mates with:
HDAF
HDAF Mates with:
HDAM

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HDAM or www.samtec.com?HDAF

Insulator Material:
Black LCP

Contact Material:
Copper Alloy

Plating:
Au or Sn over
50 μm (1.27 μm) Ni

Current Rating:
3.4 A per pin
(6 adjacent pins powered)

Operating Temp Range:
-55 °C to +125 °C

Contact Resistance: 19 mΩ

Working Voltage: 200 VAC

Mated Cycles: 100

RoHS Compliant: Yes

Lead-Free Solderable: Yes

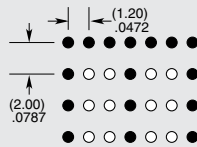
RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594

DIFFERENTIAL APPLICATIONS



ARRAY	PAIR COUNT*
11x13	44
15x13	60
23x13	92

*2:1 S:G Ratio

ALSO AVAILABLE (MOQ Required)

- Tin-Lead Solder Charge
 - Other platings
- Contact Samtec.

Note: HD Mezz is a trademark of Molex Incorporated

Note: Some lengths, styles and options are non-standard, non-returnable.

HDAM	NO. OF PINS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	OTHER OPTION
	-11, -15, -23	Specify LEAD STYLE from chart	-S = 30 μm (0.76 μm) Gold on contact area, Matte Tin on tails and guide pins	-13	-2 = Lead-Free Tin Alloy 95.5% Sn/ 3.8% Ag/ 0.7% Cu Solder Charge	-P = Pick & Place Pad

No. of Pins Per Row x (2.00) .0787 + (16.06) .632

No. of Pins Per Row x (2.00) .0787 + (11.55) .455

LEAD STYLE	A
-12.0	(14.41) .567
-17.0	(19.41) .764

• Integrated guide posts

HDAF	NO. OF PINS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	OTHER OPTION
	-11, -15, -23	Specify LEAD STYLE from chart	-S = 30 μm (0.76 μm) Gold on contact area, Matte Tin on tails and weld tabs	-13	-2 = Lead-Free Tin Alloy 95.5% Sn/ 3.8% Ag/ 0.7% Cu Solder Charge	-P = Pick & Place Pad

No. of Pins Per Row x (2.00) .0787 + (11.55) .455

No. of Pins Per Row x (2.00) .0787 + (17.92) .706

LEAD STYLE	A
-08.0	(10.51) .414
-18.0	(20.51) .807

• Integrated guide posts